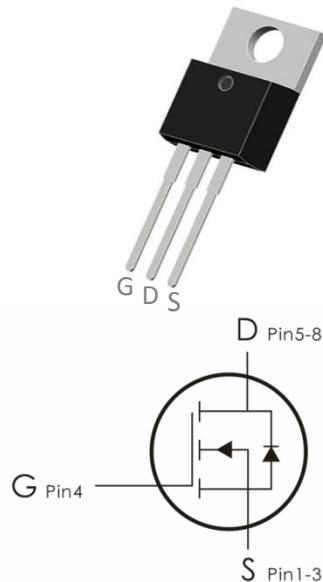


Description:

This N-Channel MOSFET uses advanced trench technology and design to provide excellent $R_{DS(on)}$ with low gate charge. It can be used in a wide variety of applications.

Features:

- 1) $V_{DS}=80V, I_D=250A, R_{DS(on)}<3.2m\Omega @V_{GS}=10V$
- 2) Low gate charge.
- 3) Green device available.
- 4) Advanced high cell density trench technology for ultra $R_{DS(on)}$.
- 5) Excellent package for good heat dissipation.



Absolute Maximum Ratings: ($T_c=25^\circ C$ unless otherwise noted)

Symbol	Parameter	Ratings	Units
V_{DS}	Drain-Source Voltage	80	V
V_{GS}	Gate-Source Voltage	± 20	V
I_D	Continuous Drain Current- $TC=25^\circ C$ ¹	250	A
	Continuous Drain Current- $TC=100^\circ C$	---	
	Pulsed Drain Current ²	750	
E_{AS}	Single Pulse Avalanche Energy ⁵	1000	mJ
P_D	Power Dissipation ³	300	W
T_J, T_{STG}	Operating and Storage Junction Temperature Range	-55 to +150	$^\circ C$

Thermal Characteristics:

Symbol	Parameter	Max	Units
R_{eJC}	Thermal Resistance,Junction to Case	0.42	$^\circ C/W$
R_{eJA}	Thermal Resistance Junction to mbient ⁴	62.5	$^\circ C/W$

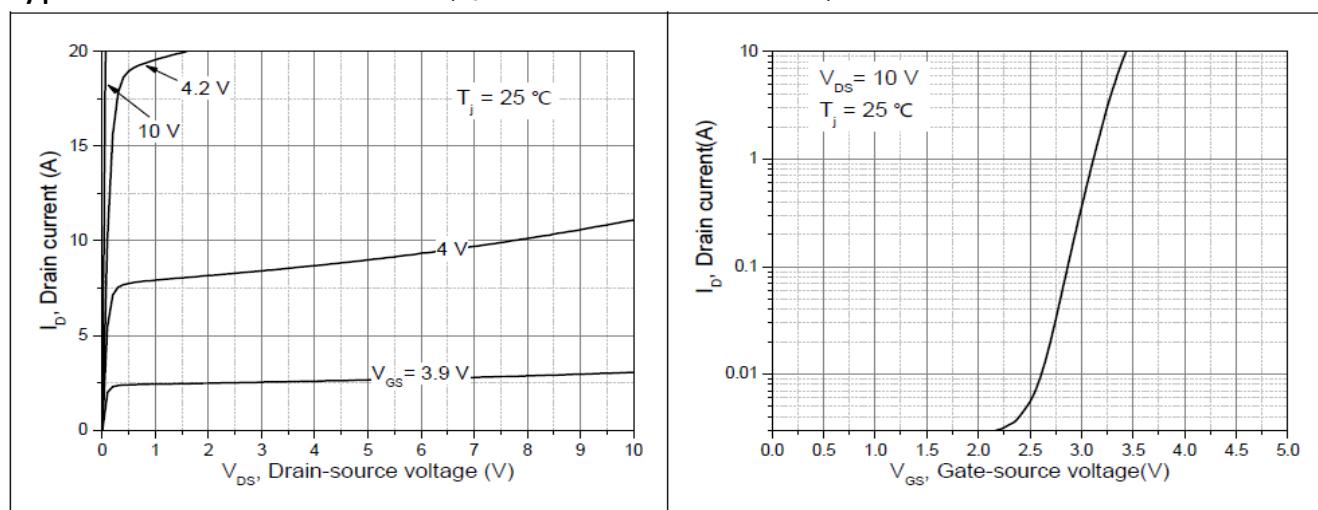
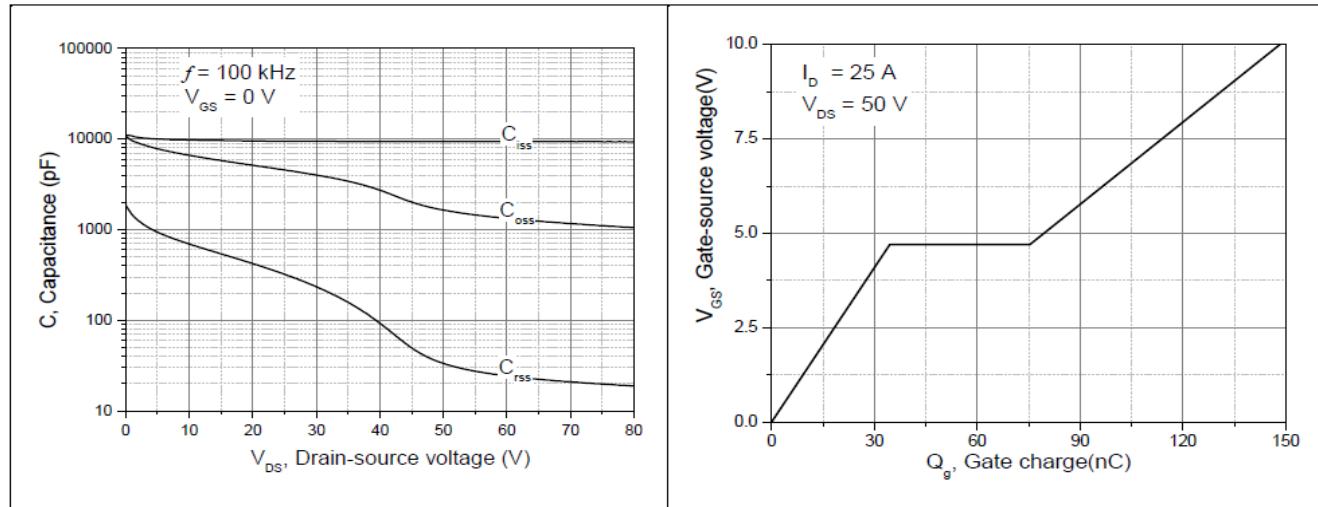
Electrical Characteristics: ($T_c=25^\circ\text{C}$ unless otherwise noted)

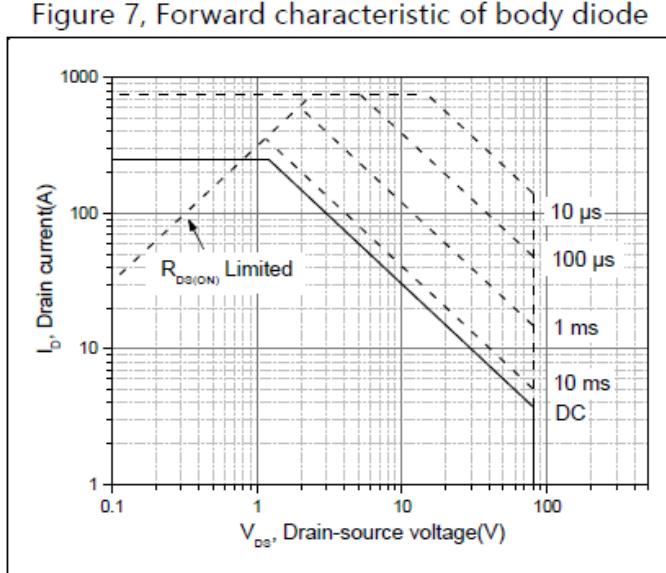
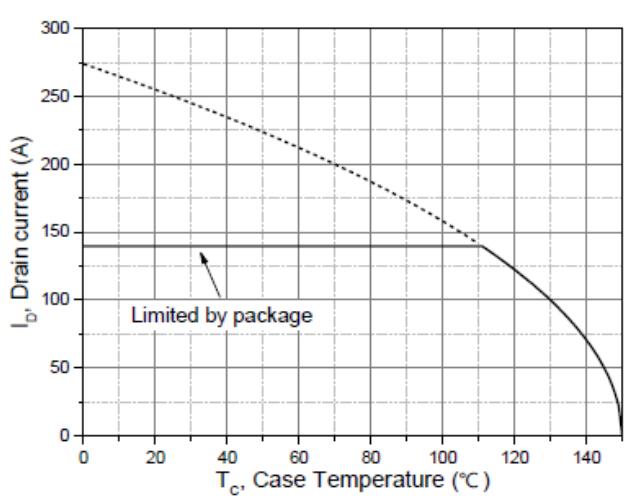
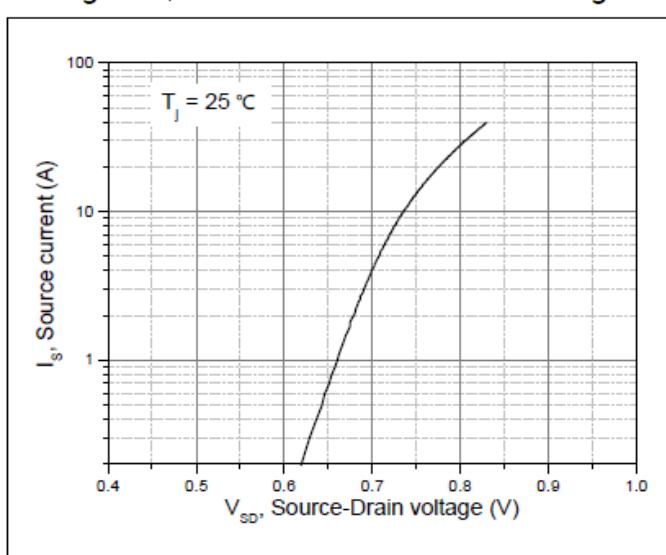
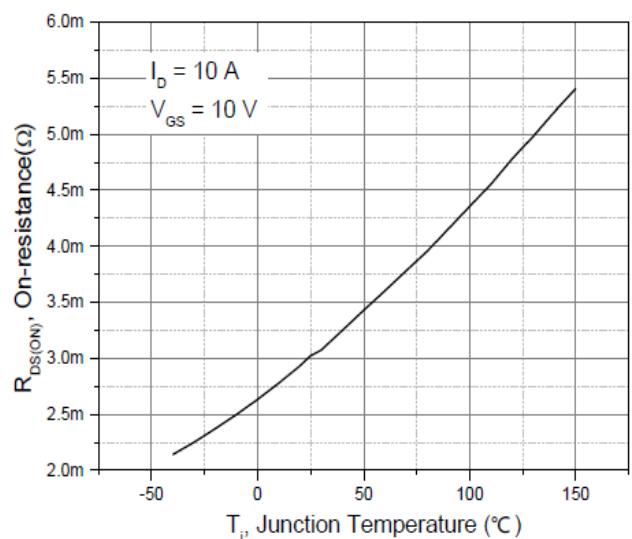
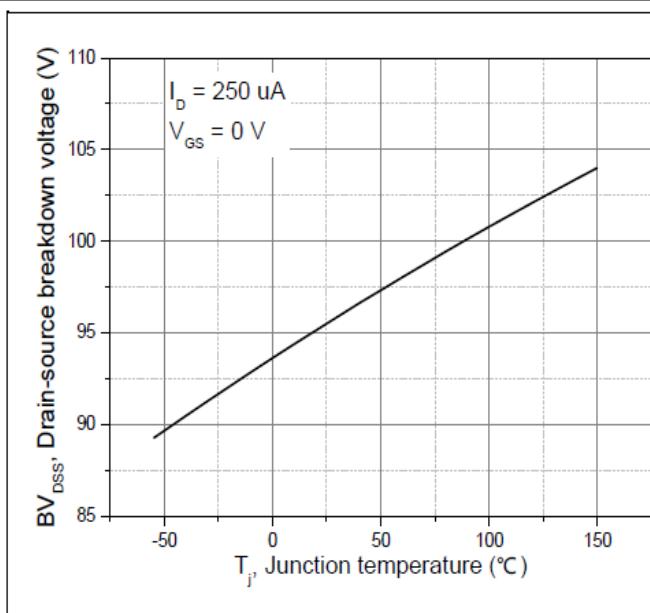
Symbol	Parameter	Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{D}}=250 \mu\text{A}$	80	---	---	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{\text{GS}}=0\text{V}, V_{\text{DS}}=80\text{V}$	---	---	1	μA
I_{GSS}	Gate-Source Leakage Current	$V_{\text{GS}}=\pm 20\text{V}, V_{\text{DS}}=0\text{A}$	---	---	± 100	nA
On Characteristics³						
$V_{\text{GS}(\text{th})}$	GATE-Source Threshold Voltage	$V_{\text{GS}}=V_{\text{DS}}, I_{\text{D}}=250 \mu\text{A}$	2	---	4	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On Resistance	$V_{\text{GS}}=10\text{V}, I_{\text{D}}=30\text{A}$	---	2.9	3.2	$\text{m}\Omega$
		$V_{\text{GS}}=4.5\text{V}, I_{\text{D}}=0\text{A}$	---	---	---	
Dynamic Characteristics⁴						
C_{iss}	Input Capacitance	$V_{\text{DS}}=40\text{V}, V_{\text{GS}}=0\text{V}, f=100\text{KHz}$	---	9322	---	pF
C_{oss}	Output Capacitance		---	2710	---	
C_{rss}	Reverse Transfer Capacitance		---	91	---	
Switching Characteristics⁴						
$t_{\text{d(on)}}$	Turn-On Delay Time	$V_{\text{DD}}=50\text{V}, I_{\text{D}}=25\text{A}, R_{\text{G}}=2\Omega$ $V_{\text{GS}}=10\text{V}$	---	36.1	---	ns
t_r	Rise Time		---	42.3	---	ns
$t_{\text{d(off)}}$	Turn-Off Delay Time		---	102.3	---	ns
t_f	Fall Time		---	30.5	---	ns
Q_g	Total Gate Charge	$V_{\text{GS}}=10\text{V}, V_{\text{DS}}=50\text{V}, I_{\text{D}}=25\text{A}$	---	148.4	---	nC
Q_{gs}	Gate-Source Charge		---	34.5	---	nC
Q_{gd}	Gate-Drain "Miller" Charge		---	40.9	---	nC
Drain-Source Diode Characteristics						
Symbol	Parameter	Conditions	Min	Typ	Max	Units
V_{SD}	Source-Drain Diode Forward Voltage	$V_{\text{GS}}=0\text{V}, I_{\text{S}}=25\text{A}$	---	---	1.3	V

LS	Continuous Source Current	V _{GS} \<V _{th}	---	---	250	A
LSp	Pulsed Source Current		---	---	750	
Trr	Reverse Recovery Time	I _S =25 A, di/dt=100 A/μs	---	108.2	---	NS
Qrr	Reverse Recovery Charge		---	428.9	---	NC

Notes:

- 1) Calculated continuous current based on maximum allowable junction temperature.
- 2) Repetitive rating; pulse width limited by max. junction temperature.
- 3) Pd is based on max. junction temperature, using junction-case thermal resistance.
- 4) The value of R_{0JA} is measured with the device mounted on 1 in 2 FR-4 board with 2oz. Copper, in a still air environment with T_a=25 °C.
- 5) V_{DD}=50 V, R_G=50 Ω, L=0.3 mH, starting T_j=25 °C.

Typical Characteristics: (T_C=25°C unless otherwise noted)

Figure 1, Typ. output characteristics
Figure 2, Typ. transfer characteristics

Figure 3, Typ. capacitances
Figure 4, Typ. gate charge



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